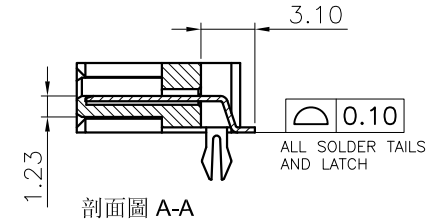
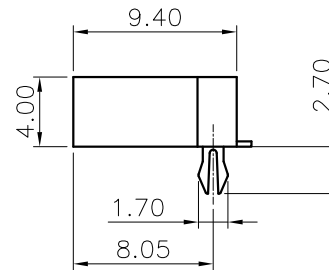


RECOMMENDED PCB LAYOUT



NOTE:

- MATERIAL :
 BASE : HIGH TEMPERATURE THERMOPLASTIC UL94V-0,
 TERMINAL: COPPER ALLOY, THICKNESS = 0.30 mm
 LATCH: COPPER ALLOY, THICKNESS = 0.30 mm
- PLATING:
 CONTACT: GOLD OVER 50u" MIN NICKEL UNDERPLATE
 SOLDER TAIL: 100u" MIN MISTY TIN 50u" MIN NICKEL UNDERPLATE. GOLD SPECIFICATION: SEE TABLE
 LATCH: 100u" MIN MISTY TIN 50u" MIN NICKEL
- ELECTRONICAL SPECIFICATION:
 CURRENT RATING: 1.5 AMPERE PER CONTACT
 CONTACT RESISTANCE: 30 MILLIOHMS MAX.
 INSULATION RESISTANCE: 1000 MEGOHMS MIN.
 DIELECTRIC WITHSTANDING VOLTAGE: 500 V AC.
 OPERATING TEMPERATURE: -20°C ~ +85°C
- MEETS THE REQUIREMENTS OF DIRECTIVE 2002/95/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL OF 27 JANUARY 2003 ON THE RESTRICTION OF THE USE OF CERTAIN HAZARDOUS SUBSTANCES IN ELECTRICAL AND ELECTRONIC EQUIPMENT (ROHS)

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±2°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審核(CH'K)	Calvin	圖名(NAME) SATA 7+15P 公座 平行三魚叉定位 反向 SMT 90度		WISCONN Technology Co., Ltd Tel: 02-2742-1798 Fax: 02-2742-1898							
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena	料號(PART NUMBER)	WSTAM-22FLBSR-R-3								
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期 DATE)	Mar. 27. 2013	圖號(DRAW NUMBER)	T006	圖檔(FILE NAME .DWG)	比例(SCALE)	1/1	圖紙(SIZE)	A4	頁次(SHEET)	1	版次(REV.)